

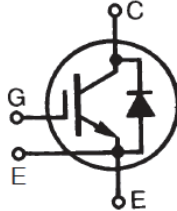


# High-frequency switch IGBT Module 1200V / 75A

Preliminary

## Features

- ◆ Fast switching field stop IGBT trench technology
- ◆ Low switching loss
- ◆ Superfast diodes
- ◆ High short circuit capability



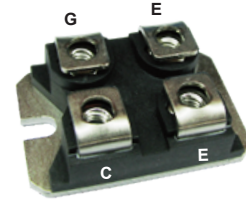
## Applications

- ◆ Welder / Power Supply
- ◆ UPS / Inverter
- ◆ Industrial Motor Drive

## Maximum Ratings (T<sub>c</sub> = 25°C)

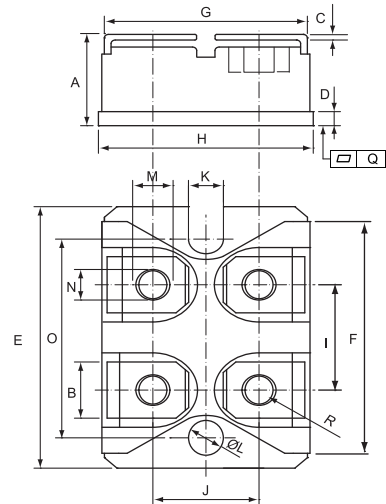
Item	Symbol	Rated Value	Unit
Collector-Emitter Voltage	V <sub>CES</sub>	1200	V
Gate-Emitter Voltage	V <sub>GES</sub>	±20	V
DC-Collector Current	T <sub>c</sub> = 80°C I <sub>C,nom.</sub>	75	A
Repetitive Peak Collector Current	t <sub>p</sub> = 1ms I <sub>CRM</sub>	150	A
Total Power Dissipation	P <sub>tot</sub>	400	W
Isolation Voltage (Terminal to Base, AC 1 min.) Between All Terminals and Baseplate	V <sub>iso</sub>	2500	V
DC Forward Current	I <sub>F</sub>	75	A
Repetitive Peak Forward Current	t <sub>p</sub> = 1ms I <sub>FRM</sub>	150	A
Junction Temperature Range	T <sub>J</sub>	- 40 ~ + 150	°C
Storage Temperature Range	T <sub>stg</sub>	- 40 ~ + 125	°C
Mounting Torque (M4 Screw)	To heatsink To terminals M <sub>d</sub>	1.3 1.1	N.m
Weight		30.5	g

## SOT-227



G = Gate, C = Collector, E = Emitter

Dimensions in inches and (millimeters)



	DIMENSIONS			
	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.460	0.483	11.68	12.28
B	0.307	0.323	7.80	8.20
C	0.030	0.033	0.75	0.85
D	0.071	0.081	1.80	2.05
E	1.488	1.504	37.80	38.20
F	1.248	1.260	31.70	32.00
G	0.917	0.957	23.30	24.30
H	0.996	1.008	25.30	25.60
I	0.579	0.602	14.70	15.30
J	0.492	0.516	12.50	13.10
K	0.161	0.169	4.10	4.30
L	0.161	0.169	4.10	4.30
M	0.181	0.197	4.60	5.00
N	0.165	0.181	4.20	4.60
O	1.181	1.197	30.00	30.40
Q	-0.002	0.004	-0.05	0.10
R	M4*8			



■ **Electrical Characteristics** (  $T_{VJ} = 25^{\circ}\text{C}$  )

Characteristic		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Collector-Emitter Cut-Off Current		$I_{CES}$	$V_{CE} = 1200\text{V}$ $V_{GE} = 0\text{V}$	-	10	500	$\mu\text{A}$
Gate-Emitter Leakage Current		$I_{GES}$	$V_{GE} = 20\text{V}$ $V_{CE} = 0\text{V}$	-	-	400	nA
Collector-Emitter Saturation Voltage		$V_{CE(sat)}$	$I_C = 75\text{A}, V_{GE} = 15\text{V}$	-	1.9	2.2	V
Gate-Emitter Threshold Voltage		$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 4\text{mA}$	4.5	5.5	6.5	V
Input Capacitance		$C_{ies}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	9.5	-	nF
Output Capacitance		$C_{oes}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	0.16	-	nF
Reverse Transfer Capacitance		$C_{res}$	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	0.14	-	nF
Switching Time	Rise Time	$t_r$	$V_{CC} = 600\text{V}$ $I_C = 75\text{A}$ $R_G = 1\Omega$ $V_{GE} = \pm 15\text{V}$	-	0.033	-	$\mu\text{s}$
	Turn-On Time	$t_{d,on}$		-	0.080	-	
	Fall Time	$t_f$		-	0.096	-	
	Turn-Off Time	$t_{d,off}$		-	0.252	-	
Turn-on Energy Loss Per Pulse		$E_{on}$	$I_C = 75\text{A}, V_{CC} = 600\text{V}$ $V_{GE} = 15\text{V}, R_G = 1\Omega$	-	0.5	-	mJ
Turn-off Energy Loss Per Pulse		$E_{off}$	Inductive load	-	4.8	-	mJ
External Gate Resistance		$R_G$	Per Switch	4.7	-	10	$\Omega$
Internal Gate Resistance		$R_G$		4.7			$\Omega$

■ **Free Wheeling Diode Ratings & Characteristics** (  $T_{VJ} = 25^{\circ}\text{C}$  )

Characteristic		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Peak Forward Voltage		$V_F$	$I_F = 75\text{A}, V_{GE} = 0\text{V}$	-	2.0	2.5	V
Peak Reverse Recovery Current		$I_{RM}$	$I_F = 75\text{A}, R_G = 1\Omega$ $V_R = 600\text{V}, V_{GE} = -15\text{V}$	-	62	-	A
Recovered Charge		$Q_r$	$I_F = 75\text{A}, R_G = 1\Omega$ $V_R = 600\text{V}, V_{GE} = -15\text{V}$	-	4.3	-	$\mu\text{C}$
Reverse Recovery Energy		$E_{rec}$	$I_F = 75\text{A}, R_G = 1\Omega$ $V_R = 600\text{V}, V_{GE} = -15\text{V}$	-	2.9	-	mJ
Reverse Recovery Time		$T_{rr}$	$I_F = 75\text{A}, R_G = 1\Omega$ $V_R = 300\text{V}, V_{GE} = -15\text{V}$	-	90	-	ns

■ **Thermal Characteristics** (  $T_C = 25^{\circ}\text{C}$  )

Characteristic		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Thermal Impedance	IGBT	$R_{th(j-c)}$	Junction to Case	-	-	0.30	$^{\circ}\text{C/W}$
	Diode			-	-	0.55	



Typical Characteristics

Preliminary Data

Fig.1 Output characteristic (Typical)

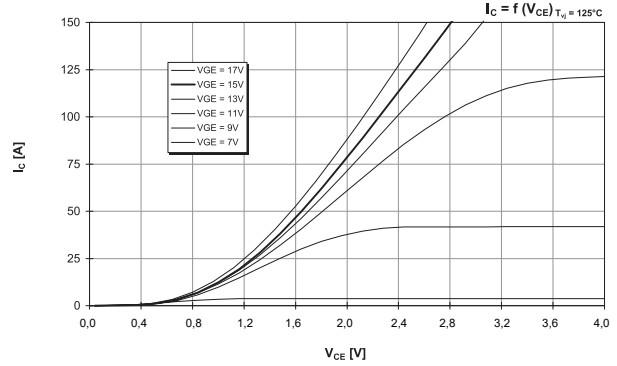
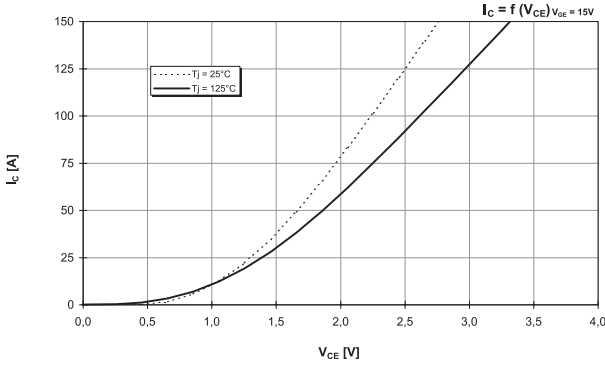


Fig.2 Transfer characteristic (Typical)

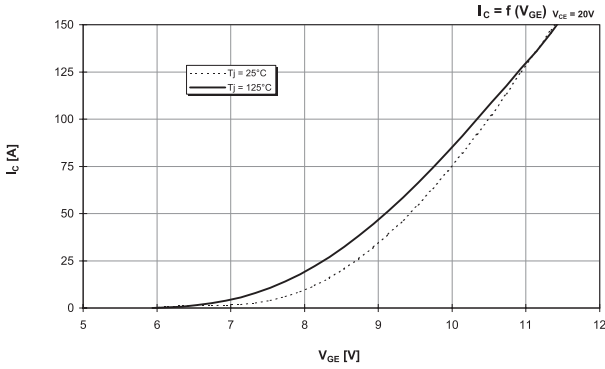


Fig.3 Forward characteristic of inverse diode (typical)

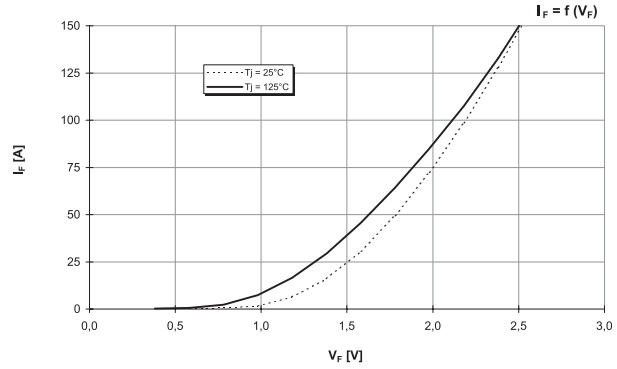


Fig.4 Switching losses (Typical)

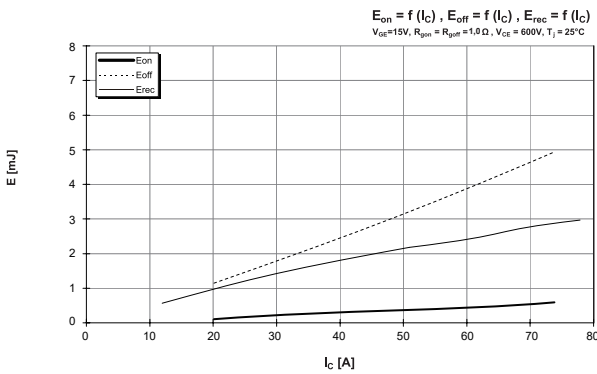


Fig.5 Switching losses IGBT, Inverter (typical)

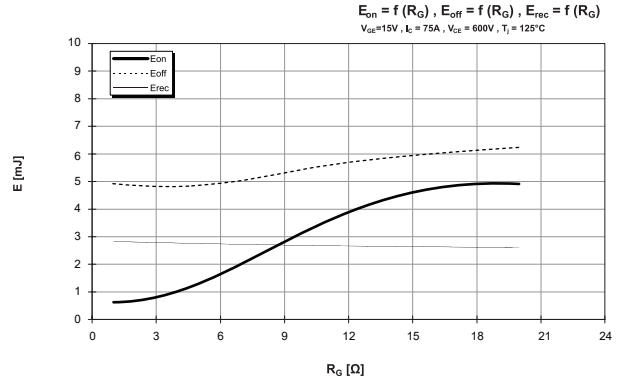
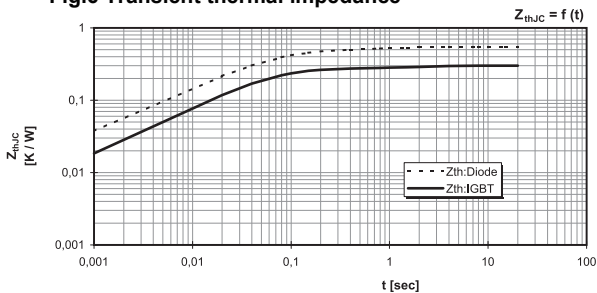
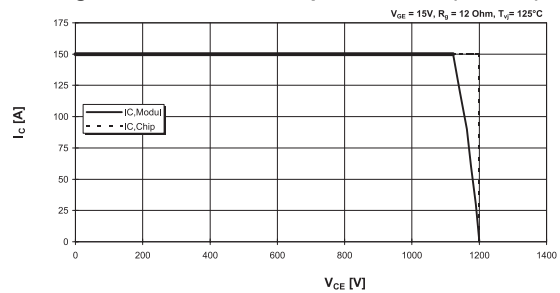


Fig.6 Transient thermal impedance



i	1	2	3	4
$r_i$ [K/kW] : IGBT	20,13	60,93	79,4	19,54
$\tau_i$ [sec] : IGBT	0,002	0,03	0,066	1,655
$r_i$ [K/kW] : Diode	65,43	173,31	189,08	72,18
$\tau_i$ [sec] : Diode	0,002	0,03	0,072	0,682

Fig.7 Reverse bias safe operation area (RBSOA)





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